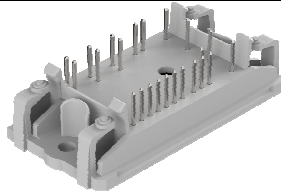
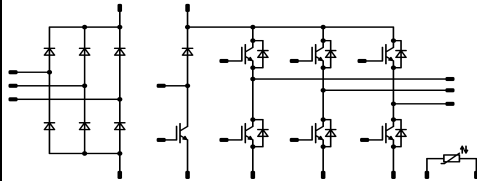




flow PIM 0		600 V / 30 A
Features	• Vincotech clip-in housing • Trench Fieldstop IGBT's for low saturation losses	flow 0 17mm housing 
Target Applications	• Industrial Drives • Embedded Generation	
Types	• V23990-P546-A20-PM	
		Schematic 

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Rectifier Diode				
Repetitive peak reverse voltage	V_{RRM}		1600	V
DC forward current	I_{FAV}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	34	A
Surge (non-repetitive) forward current	I_{FSM}	$t_p = 10\text{ ms}$ $T_j = 150\text{ °C}$	200	A
I^2t -value	I^2t	50 Hz half sine wave	200	A ² s
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	43	W
Maximum Junction Temperature	T_{jmax}		150	°C
Inverter Switch				
Collector-emitter breakdown voltage	V_{CE}		600	V
DC collector current	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	31	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	90	A
Turn off safe operating area		$V_{CE} \leq 1200V$, $T_j \leq T_{op\text{ max}}$	90	A
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	64	W
Gate-emitter peak voltage	V_{GE}		±20	V
Short circuit ratings	t_{SC}	$T_j \leq 150\text{ °C}$	6	μs
	V_{CC}	$V_{GE} = 15\text{ V}$	360	V
Maximum Junction Temperature	T_{jmax}		175	°C



Maximum Ratings

$T_J = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
-----------	--------	-----------	-------	------

Inverter Diode

Peak Repetitive Reverse Voltage	V_{RRM}		600	V
DC forward current	I_F	$T_J = T_{Jmax}$ $T_s = 80\text{ °C}$	31	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{Jmax}	60	A
Power dissipation	P_{tot}	$T_J = T_{Jmax}$ $T_s = 80\text{ °C}$	53	W
Maximum Junction Temperature	T_{Jmax}		175	°C

Brake Switch

Collector-emitter breakdown voltage	V_{CE}		600	V
DC collector current	I_C	$T_J = T_{Jmax}$ $T_s = 80\text{ °C}$	26	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{Jmax}	60	A
Turn off safe operating area		$V_{CE} \leq 1200\text{ V}$, $T_J \leq T_{op\ max}$	60	A
Power dissipation	P_{tot}	$T_J = T_{Jmax}$ $T_s = 80\text{ °C}$	56	W
Gate-emitter peak voltage	V_{GE}		± 20	V
Short circuit ratings	t_{SC} V_{CC}	$T_J \leq 150\text{ °C}$ $V_{GE} = 15\text{ V}$	6 360	μs V
Maximum Junction Temperature	T_{Jmax}		175	°C

Brake Diode

Peak Repetitive Reverse Voltage	V_{RRM}		600	V
DC forward current	I_F	$T_J = T_{Jmax}$ $T_s = 80\text{ °C}$	21	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{Jmax}	40	A
Power dissipation	P_{tot}	$T_J = T_{Jmax}$ $T_s = 80\text{ °C}$	37	W
Maximum Junction Temperature	T_{Jmax}		175	°C

Thermal Properties

Storage temperature	T_{sig}		-40...+125	°C
Operation temperature under switching condition	T_{op}		-40...+($T_{Jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{is}	$t = 2\text{ s}$ DC voltage	4000	V
Creepage distance			min 12,7	mm
Clearance			10,07	mm
Comparative tracking index	CTI		>200	



Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_F [V] V_{CE} [V] V_{DS} [V]	I_C [A] I_F [A] I_D [A]	T_j [°C]	Min	Typ	Max	
Rectifier Diode										
Forward voltage	V_F				30	25 125	0,8	1,20 1,17	1,8	V
Threshold voltage (for power loss calc. only)	V_{to}				30	25 125		0,93 0,80		V
Slope resistance (for power loss calc. only)	r_t				30	25 125		11 15		mΩ
Reverse current	I_r			1600		25			0,05	mA
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,61		K/W
Inverter Switch										
Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,00043	25	5	5,8	6,5	V
Collector-emitter saturation voltage	V_{CEsat}		15		30	25 150	1,1	1,67 1,90	1,9	V
Collector-emitter cut-off current incl. Diode	I_{CES}		0	600		25			0,0016	mA
Gate-emitter leakage current	I_{GES}		20	0		25			300	nA
Integrated Gate resistor	R_{gint}							none		Ω
Turn-on delay time	$t_{d(on)}$	$R_{goff} = 4\ \Omega$ $R_{gon} = 8\ \Omega$	15	300	30	25 150		17 18		ns
Rise time	t_r					25 150		16 18		
Turn-off delay time	$t_{d(off)}$					25 150		156 172		
Fall time	t_f					25 150		88 101		
Turn-on energy loss	E_{on}					25 150		0,52 0,71		mWs
Turn-off energy loss	E_{off}	25 150		0,72 0,90						
Input capacitance	C_{ies}	f = 1 MHz	0	25		25		1630		pF
Output capacitance	C_{oss}							108		
Reverse transfer capacitance	C_{rss}							50		
Gate charge	Q_G		±15	480	30	25		167		nC
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,49		K/W
Inverter Diode										
Diode forward voltage	V_F	$R_{gon} = 8\ \Omega$	15	300	30	25 150	1,25	1,64 1,66	1,95	V
Peak reverse recovery current	I_{RRM}					25 150		25 28		A
Reverse recovery time	t_{rr}					25 150		176 256		ns
Reverse recovered charge	Q_{rr}					25 150		1,36 2,45		μC
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 150		1521 932		A/μs
Reverse recovered energy	E_{rec}					25 150		0,27 0,51		mWs
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,81		K/W



Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_F [V] V_{CE} [V] V_{DS} [V]	I_C [A] I_F [A] I_D [A]	T_j [°C]	Min	Typ	Max	
Brake Switch										
Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,00029	25	5	5,8	6,5	V
Collector-emitter saturation voltage	V_{CEsat}		15		20	25 150	1	1,58 1,76	2,2	V
Collector-emitter cut-off incl diode	I_{CES}		0	600		25			0,0011	mA
Gate-emitter leakage current	I_{GES}		20	0		25			300	nA
Integrated Gate resistor	R_{gint}							none		Ω
Turn-on delay time	$t_{d(on)}$	$R_{goff} = 8\ \Omega$ $R_{gon} = 16\ \Omega$	± 15	300	20	25 150		15 14		ns
Rise time	t_r					25 150		12 15		
Turn-off delay time	$t_{d(off)}$					25 150		197 220		
Fall time	t_f					25 150		100 119		
Turn-on energy loss	E_{on}					25 150		0,31 0,43		mWs
Turn-off energy loss	E_{off}					25 150		0,53 0,67		
Input capacitance	C_{ies}	$f = 1\ \text{MHz}$	0	25		25		1100		pF
Output capacitance	C_{oss}							71		
Reverse transfer capacitance	C_{rss}							32		
Gate charge	Q_G		± 15	480	20	25		120		nC
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 3,4\ \text{W/mK (PSX)}$						1,70		K/W
Brake Diode										
Diode forward voltage	V_F				20	25 150	1,25	1,83 1,76	1,95	V
Reverse leakage current	I_r			600		25			27	μA
Peak reverse recovery current	I_{RRM}	$R_{gon} = 16\ \Omega$	± 15	300	20	25 150		18 21		A
Reverse recovery time	t_{rr}					25 150		31 197		ns
Reverse recovered charge	Q_{rr}					25 150		0,39 0,39		μC
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 150		1762 927		A/μs
Reverse recovery energy	E_{rec}					25 150		0,05 0,25		mWs
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 3,4\ \text{W/mK (PSX)}$						2,60		K/W
Thermistor										
Rated resistance	R					25		22000		Ω
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 1486\ \Omega$				100	-5		5	%
Power dissipation	P					25		210		mW
Power dissipation constant						25		3,5		mW/K
B-value	$B_{(25/50)}$	Tol. $\pm 3\%$				25				K
B-value	$B_{(25/100)}$	Tol. $\pm 3\%$				25		4000		K
Vincotech NTC Reference						25			A	

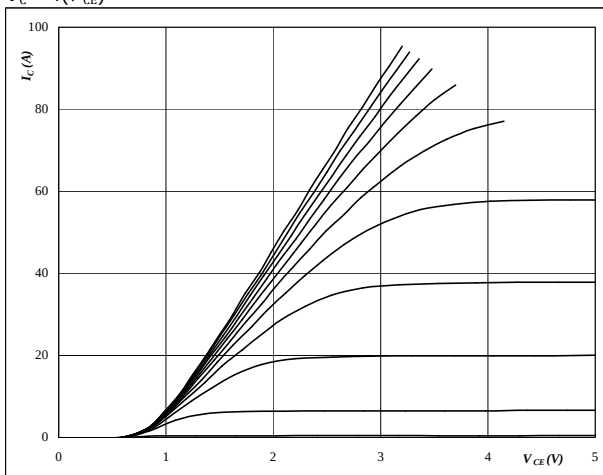


Inverter Characteristics

figure 1. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$



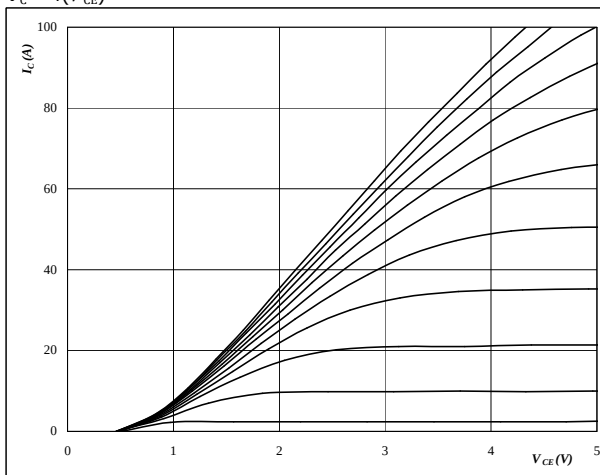
At

$t_p = 250 \mu s$
 $T_j = 25^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 2. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$



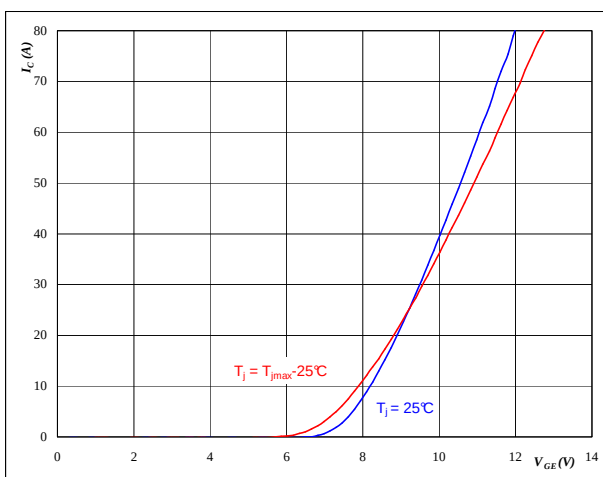
At

$t_p = 250 \mu s$
 $T_j = 125^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$



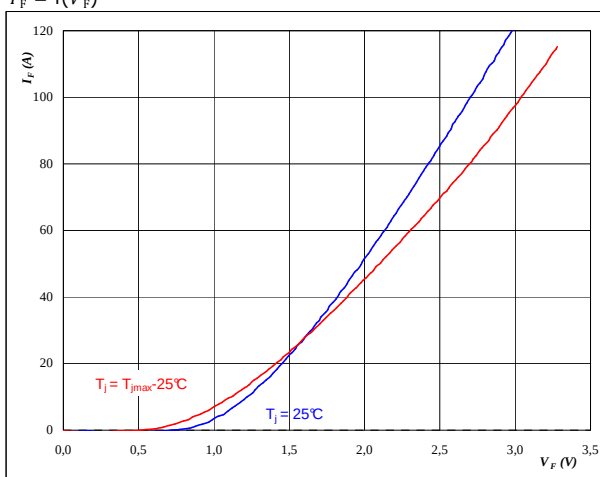
At

$t_p = 250 \mu s$
 $V_{CE} = 10 V$

figure 4. FWD

Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$



At

$t_p = 250 \mu s$



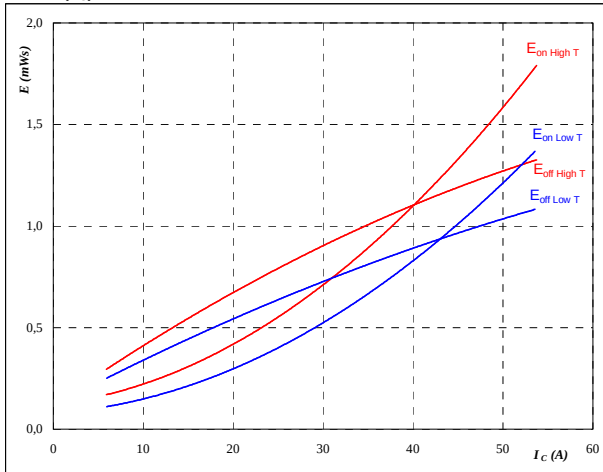
Inverter Characteristics

figure 5.

IGBT

Typical switching energy losses
as a function of collector current

$$E = f(I_C)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

$$R_{gon} = 8 \text{ } \Omega$$

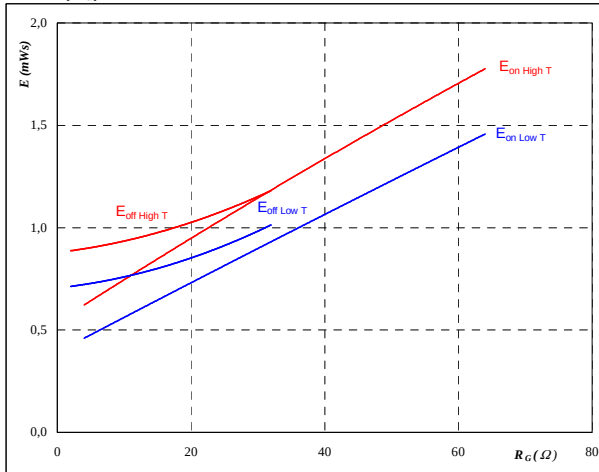
$$R_{goff} = 4 \text{ } \Omega$$

figure 6.

IGBT

Typical switching energy losses
as a function of gate resistor

$$E = f(R_G)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

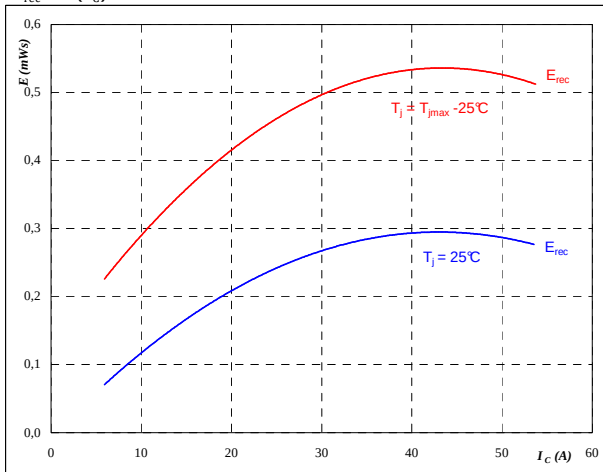
$$I_C = 30 \text{ A}$$

figure 7.

FWD

Typical reverse recovery energy loss
as a function of collector current

$$E_{rec} = f(I_C)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

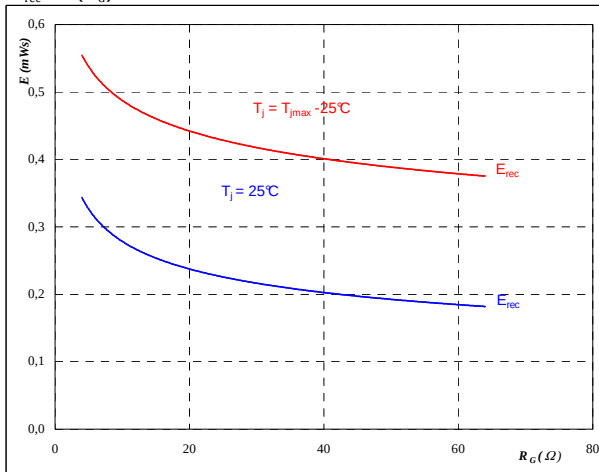
$$R_{gon} = 8 \text{ } \Omega$$

figure 8.

FWD

Typical reverse recovery energy loss
as a function of gate resistor

$$E_{rec} = f(R_G)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

$$I_C = 30 \text{ A}$$



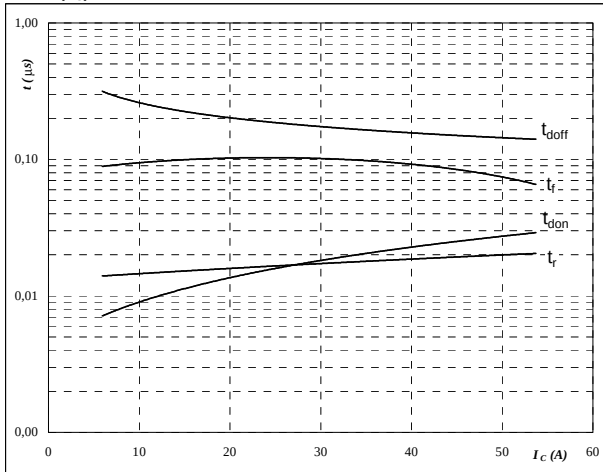
Inverter Characteristics

figure 9.

IGBT

Typical switching times as a
function of collector current

$$t = f(I_C)$$



With an inductive load at

$$T_j = 125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

$$R_{gon} = 8 \text{ } \Omega$$

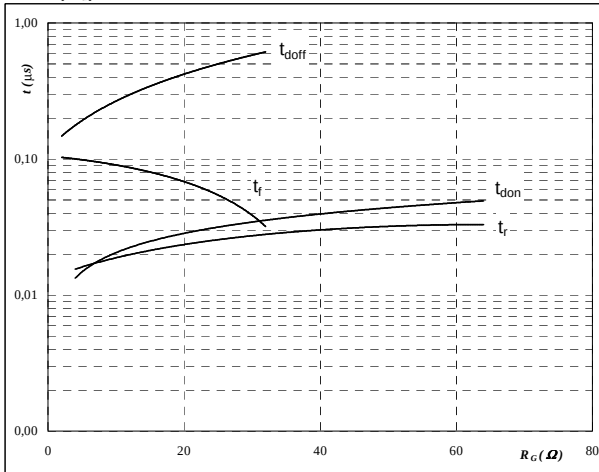
$$R_{goff} = 4 \text{ } \Omega$$

figure 10.

IGBT

Typical switching times as a
function of gate resistor

$$t = f(R_G)$$



With an inductive load at

$$T_j = 125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

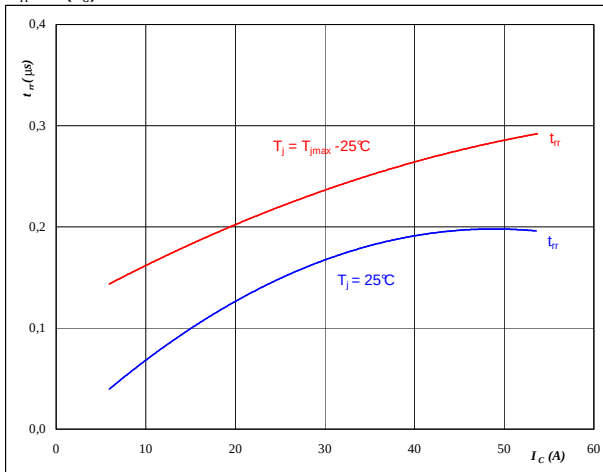
$$I_C = 30 \text{ A}$$

figure 11.

FWD

Typical reverse recovery time as a
function of collector current

$$t_{rr} = f(I_C)$$



At

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

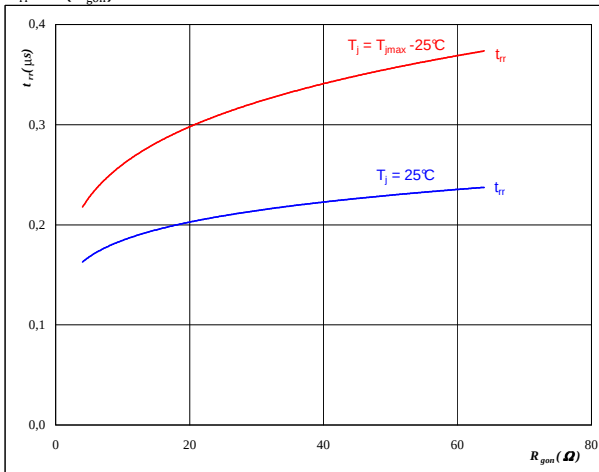
$$R_{gon} = 8 \text{ } \Omega$$

figure 12.

FWD

Typical reverse recovery time as a
function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



At

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_R = 300 \text{ V}$$

$$I_F = 30 \text{ A}$$

$$V_{GE} = 15 \text{ V}$$



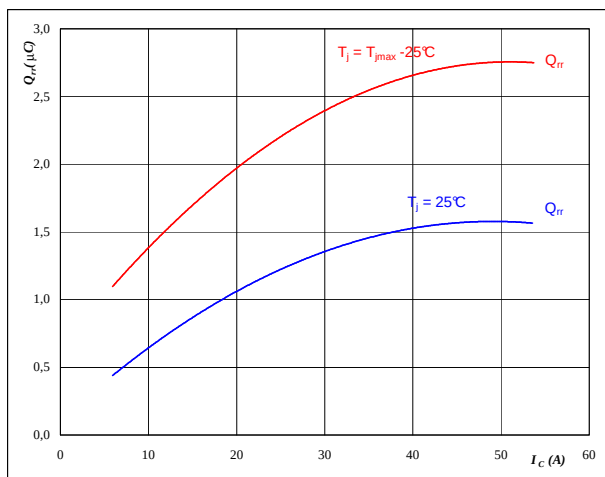
Inverter Characteristics

figure 13.

FWD

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_C)$$



At

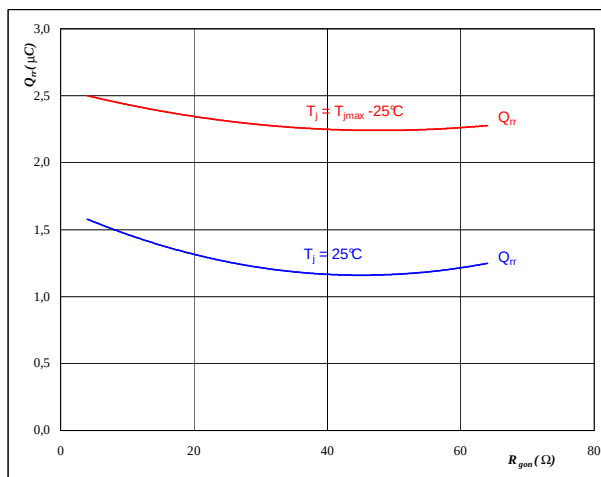
$T_j =$	25/125	°C
$V_{CE} =$	300	V
$V_{GE} =$	15	V
$R_{gon} =$	8	Ω

figure 14.

FWD

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$



At

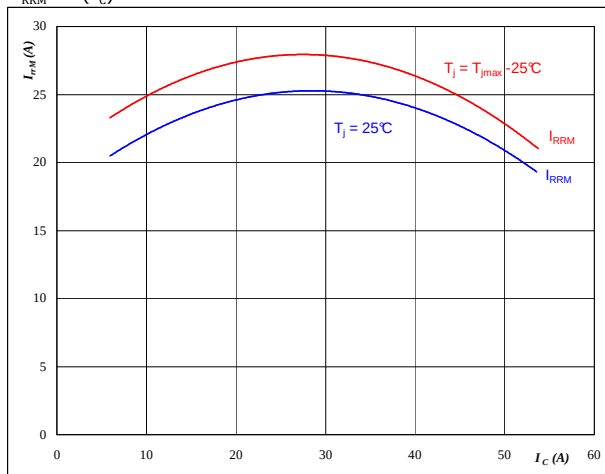
$T_j =$	25/125	°C
$V_R =$	300	V
$I_F =$	30	A
$V_{GE} =$	15	V

figure 15.

FWD

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_C)$$



At

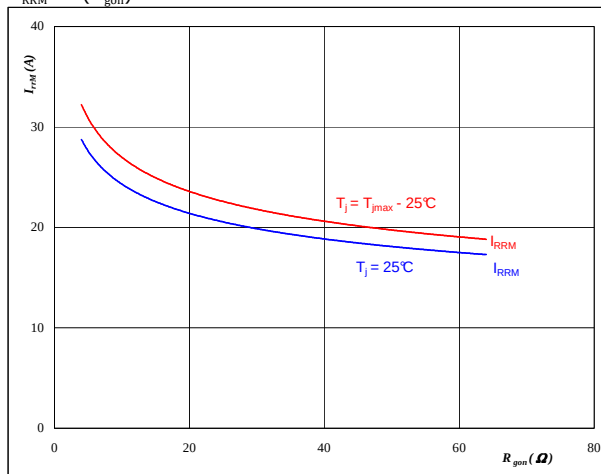
$T_j =$	25/125	°C
$V_{CE} =$	300	V
$V_{GE} =$	15	V
$R_{gon} =$	8	Ω

figure 16.

FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$



At

$T_j =$	25/125	°C
$V_R =$	300	V
$I_F =$	30	A
$V_{GE} =$	15	V

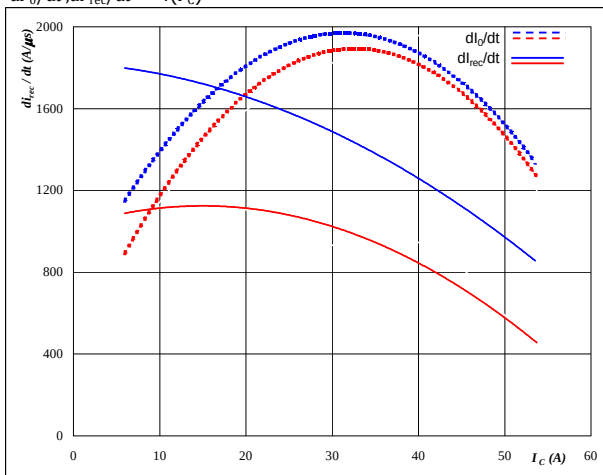


Inverter Characteristics

figure 17. FWD

Typical rate of fall of forward
and reverse recovery current as a
function of collector current

$$dI_0/dt, dI_{rec}/dt = f(I_C)$$



At

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

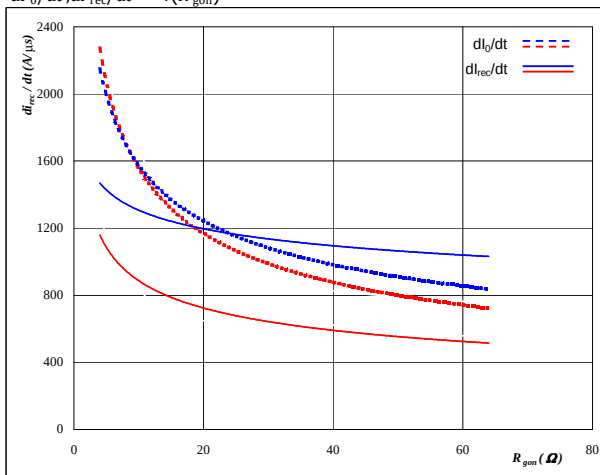
$$V_{GE} = 15 \text{ V}$$

$$R_{gon} = 8 \text{ } \Omega$$

figure 18. FWD

Typical rate of fall of forward
and reverse recovery current as a
function of IGBT turn on gate resistor

$$dI_0/dt, dI_{rec}/dt = f(R_{gon})$$



At

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_R = 300 \text{ V}$$

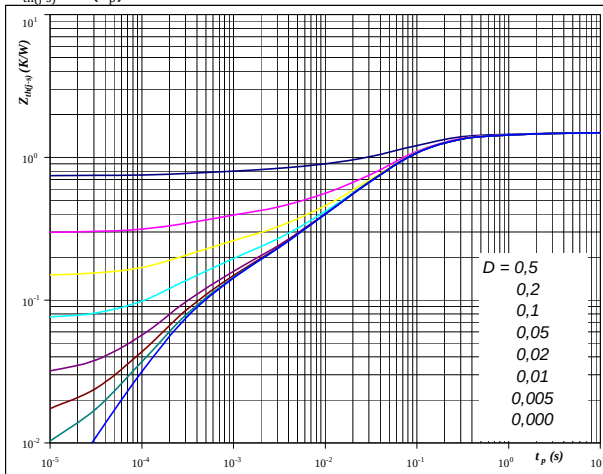
$$I_F = 30 \text{ A}$$

$$V_{GE} = 15 \text{ V}$$

figure 19. IGBT

IGBT transient thermal impedance
as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At

$$D = t_p / T$$

$$R_{th(j-s)} = 1,49 \text{ K/W}$$

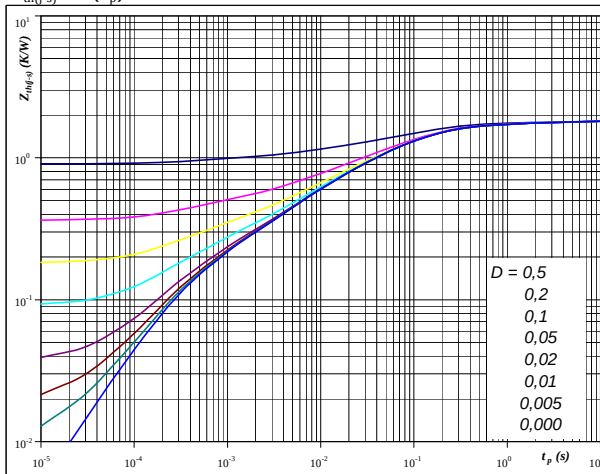
IGBT thermal model values

R (K/W)	Tau (s)
7,25E-02	2,02E+00
1,02E-01	4,53E-01
6,96E-01	8,91E-02
3,56E-01	3,19E-02
1,42E-01	5,59E-03
4,77E-02	9,74E-04
7,51E-02	2,56E-04

figure 20. FWD

FWD transient thermal impedance
as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At

$$D = t_p / T$$

$$R_{th(j-s)} = 1,81 \text{ K/W}$$

FWD thermal model values

R (K/W)	Tau (s)
8,32E-02	4,59E+00
2,00E-01	4,81E-01
7,57E-01	9,25E-02
4,20E-01	1,80E-02
2,12E-01	3,31E-03
1,39E-01	3,46E-04



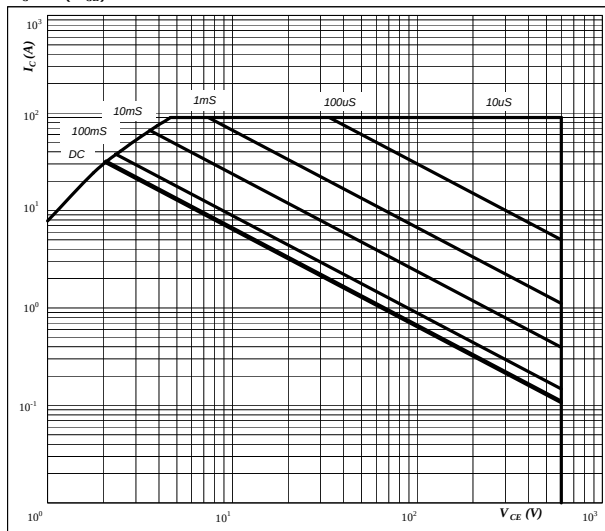
Inverter Characteristics

figure 25.

IGBT

Safe operating area as a function
of collector-emitter voltage

$$I_C = f(V_{CE})$$



At

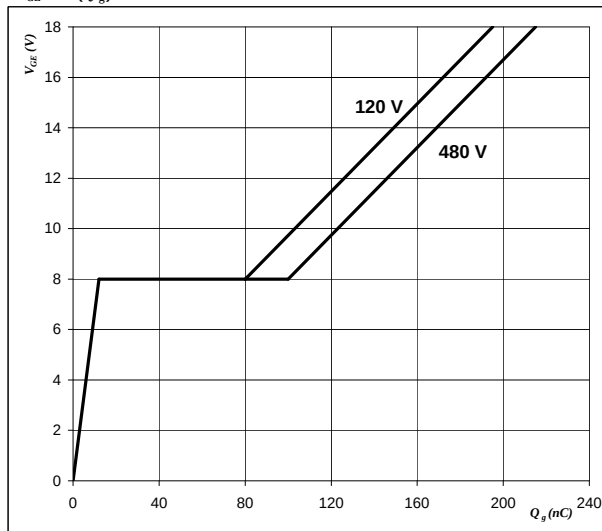
$D =$ single pulse
 $T_s =$ 80 °C
 $V_{GE} =$ 15 V
 $T_j = T_{jmax}$

figure 26.

IGBT

Gate voltage vs Gate charge

$$V_{GE} = f(Q_g)$$



At

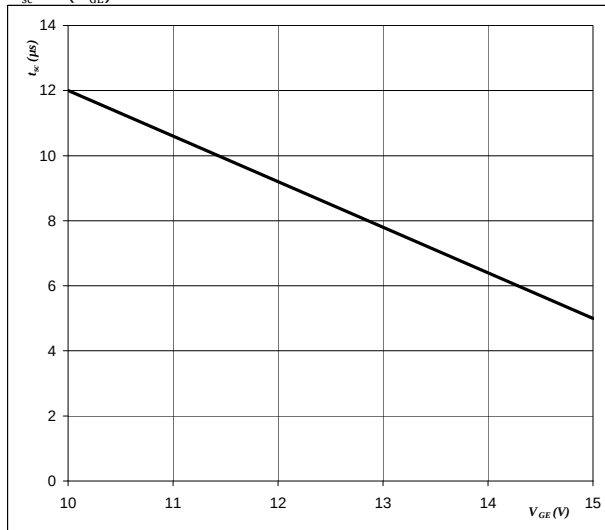
$I_C =$ 30 A

figure 27.

IGBT

Short circuit withstand time as a function of
gate-emitter voltage

$$t_{sc} = f(V_{GE})$$



At

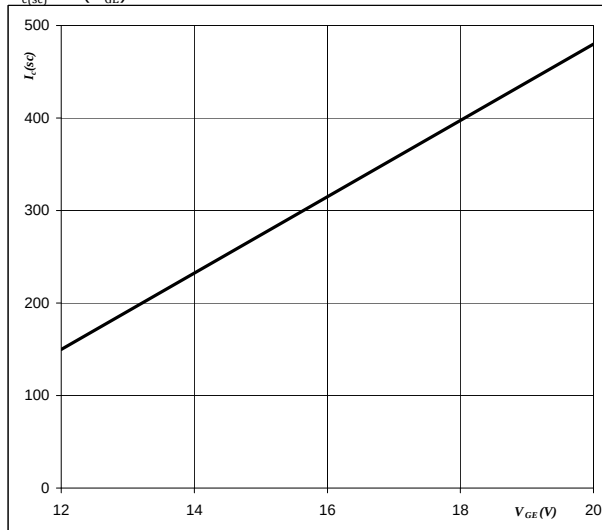
$V_{CE} =$ 600 V
 $T_j \leq$ 175 °C

figure 28.

IGBT

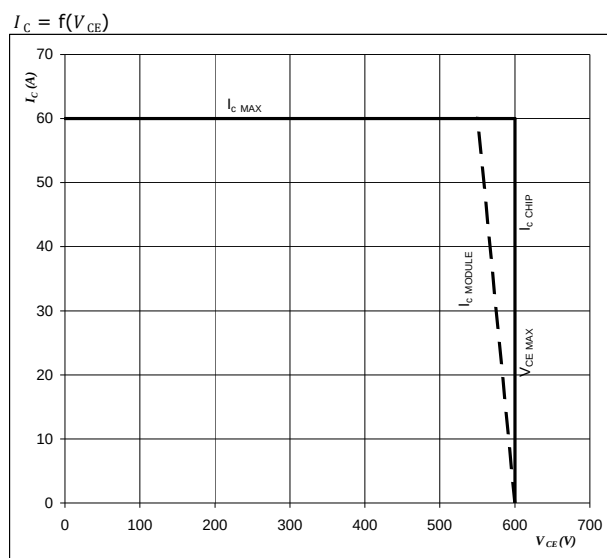
Typical short circuit collector current as a function of
gate-emitter voltage

$$I_{C(sc)} = f(V_{GE})$$



At

$V_{CE} \leq$ 600 V
 $T_j =$ 175 °C

**figure 29.****IGBT****Reverse bias safe operating area****At**

$$T_j = T_{j\text{max}} - 25 \text{ } ^\circ\text{C}$$

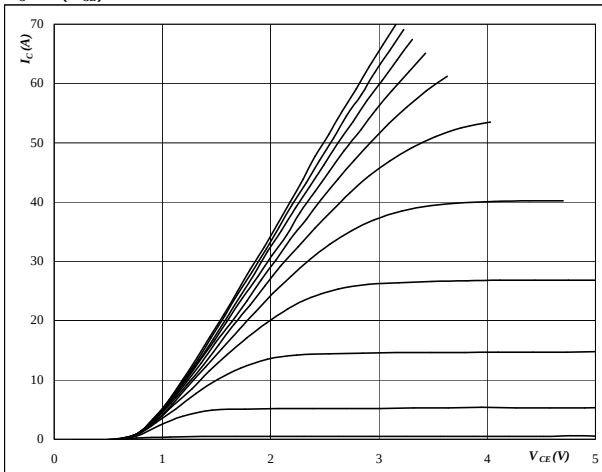
Switching mode : 3phase SPWM



Brake Characteristics

figure 1. IGBT**Typical output characteristics**

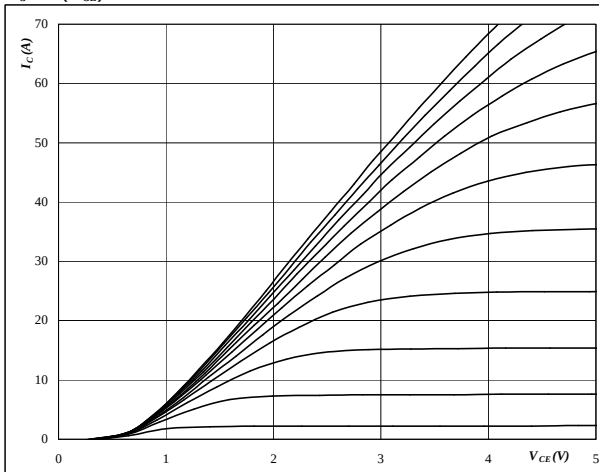
$$I_C = f(V_{CE})$$

**At**

$t_p = 250 \mu s$
 $T_j = 25 ^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 2. IGBT**Typical output characteristics**

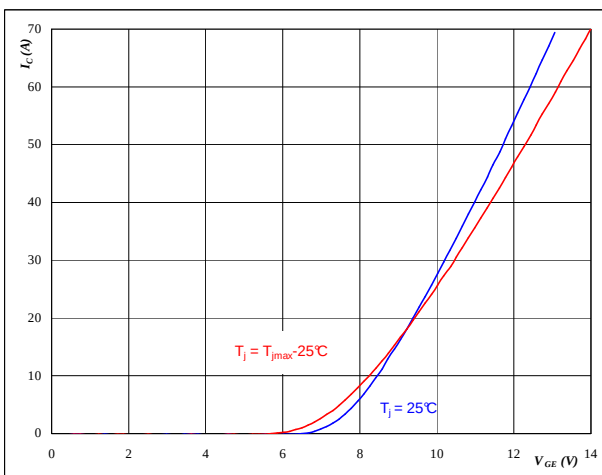
$$I_C = f(V_{CE})$$

**At**

$t_p = 250 \mu s$
 $T_j = 125 ^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT**Typical transfer characteristics**

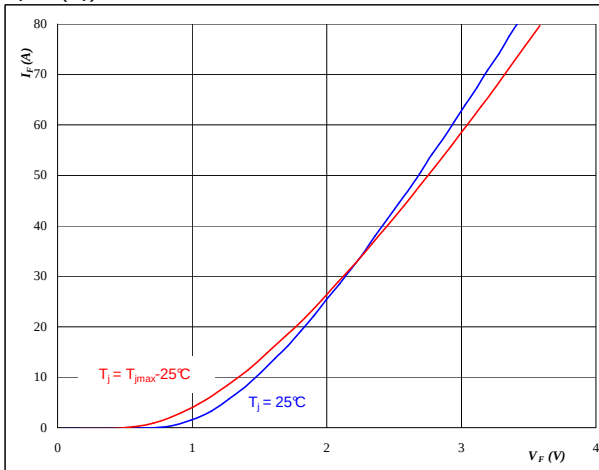
$$I_C = f(V_{GE})$$

**At**

$t_p = 250 \mu s$
 $V_{CE} = 10 V$

figure 4. FWD**Typical diode forward current as a function of forward voltage**

$$I_F = f(V_F)$$

**At**

$t_p = 250 \mu s$

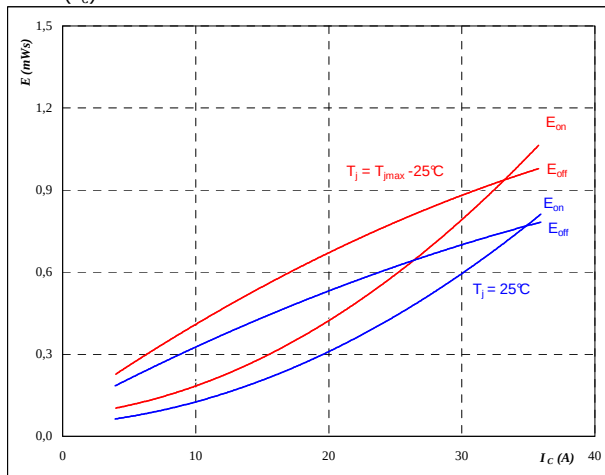


Brake Characteristics

figure 5. IGBT

Typical switching energy losses
as a function of collector current

$$E = f(I_C)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

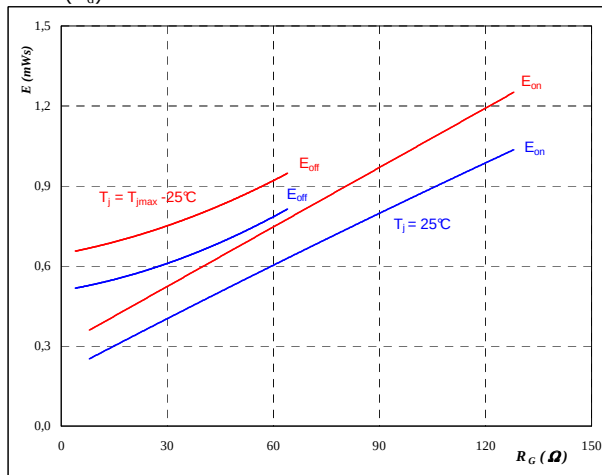
$$R_{gon} = 16 \text{ } \Omega$$

$$R_{goff} = 8 \text{ } \Omega$$

figure 6. IGBT

Typical switching energy losses
as a function of gate resistor

$$E = f(R_G)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

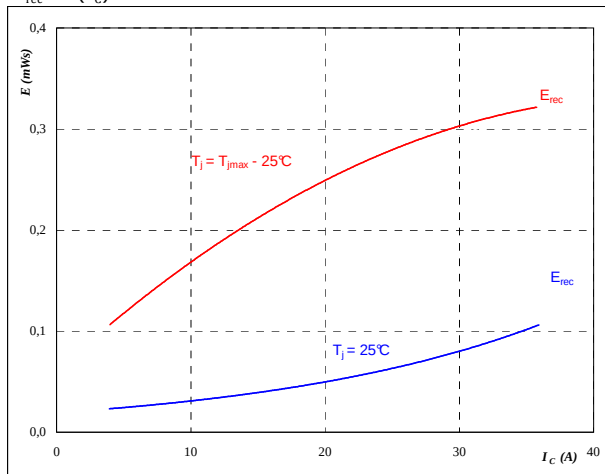
$$V_{GE} = 15 \text{ V}$$

$$I_C = 20 \text{ A}$$

figure 7. FWD

Typical reverse recovery energy loss
as a function of collector current

$$E_{rec} = f(I_C)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

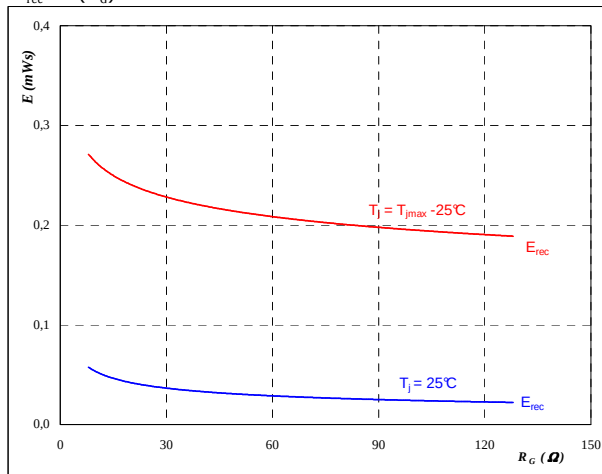
$$V_{GE} = 15 \text{ V}$$

$$R_{gon} = 16 \text{ } \Omega$$

figure 8. FWD

Typical reverse recovery energy loss
as a function of gate resistor

$$E_{rec} = f(R_G)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

$$I_C = 20 \text{ A}$$



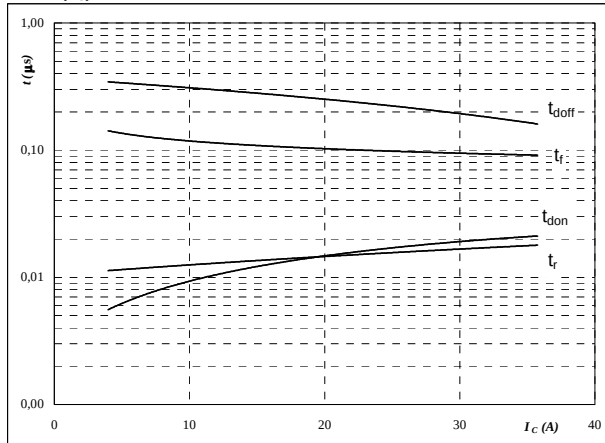
Brake Characteristics

figure 9.

IGBT

Typical switching times as a function of collector current

$$t = f(I_C)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

$$R_{gon} = 16 \text{ } \Omega$$

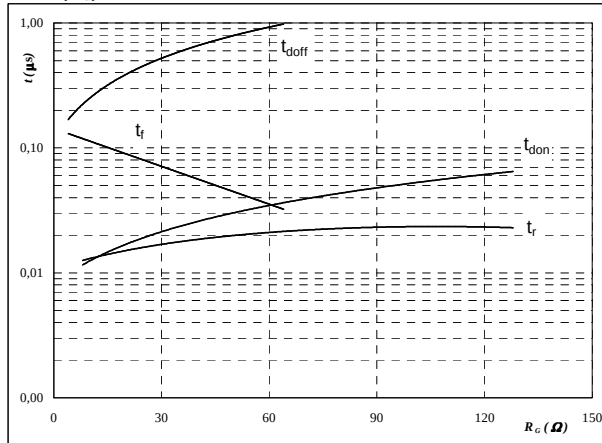
$$R_{goff} = 8 \text{ } \Omega$$

figure 10.

IGBT

Typical switching times as a function of gate resistor

$$t = f(R_G)$$



With an inductive load at

$$T_j = 25/125 \text{ } ^\circ\text{C}$$

$$V_{CE} = 300 \text{ V}$$

$$V_{GE} = 15 \text{ V}$$

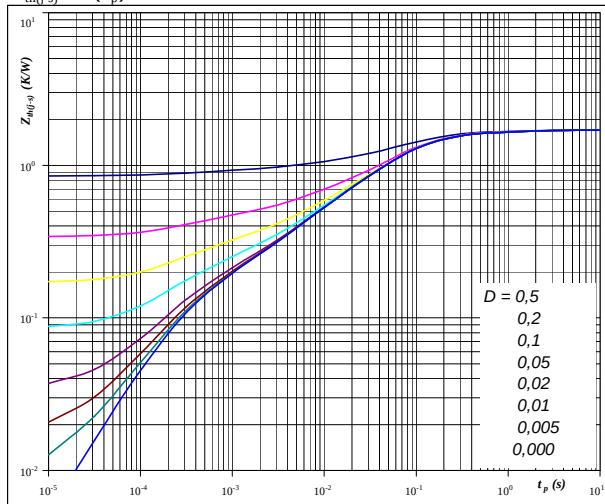
$$I_C = 20 \text{ A}$$

figure 11.

IGBT

IGBT transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At

$$D = t_p / T$$

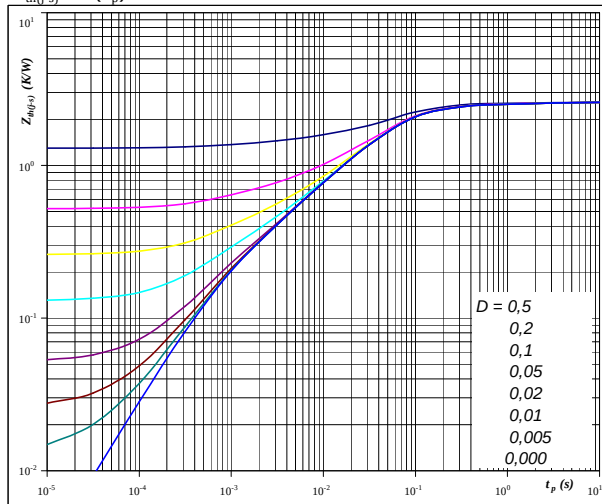
$$R_{th(j-s)} = 1,70 \text{ K/W}$$

figure 12.

FWD

FWD transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At

$$D = t_p / T$$

$$R_{th(j-s)} = 2,60 \text{ K/W}$$

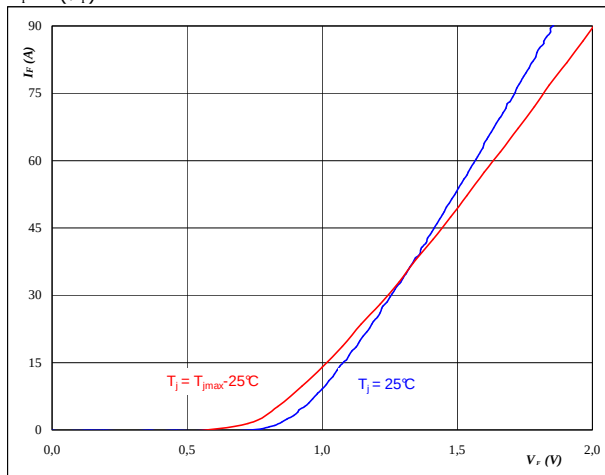


Rectifier Diode

figure 1. Rectifier Diode

Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$



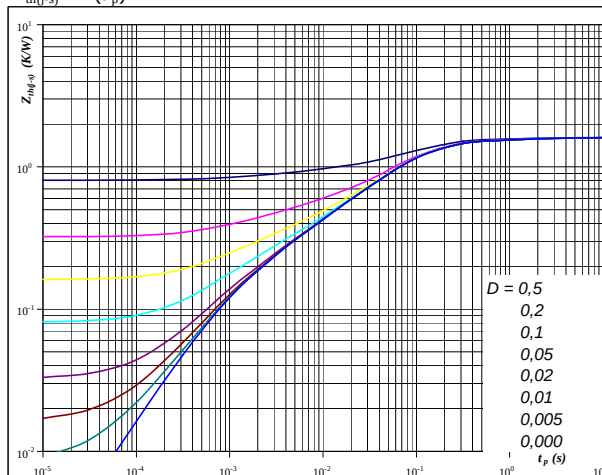
At

$$t_p = 250 \mu s$$

figure 2. Rectifier Diode

Diode transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At

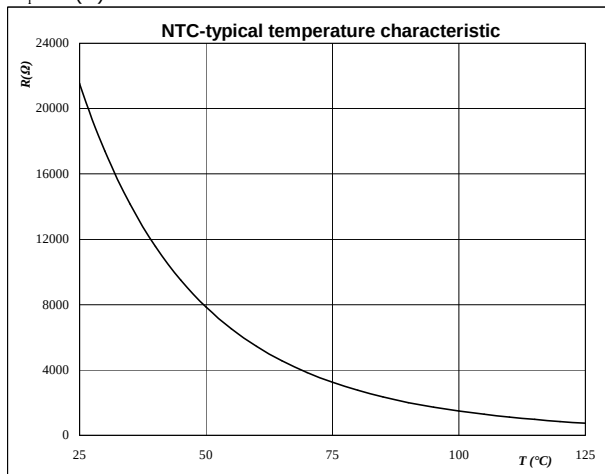
$$D = t_p / T$$
$$R_{th(j-s)} = 1,61 \text{ K/W}$$

Thermistor

figure 1. Thermistor

Typical NTC characteristic as a function of temperature

$$R_T = f(T)$$





Switching Definitions Inverter

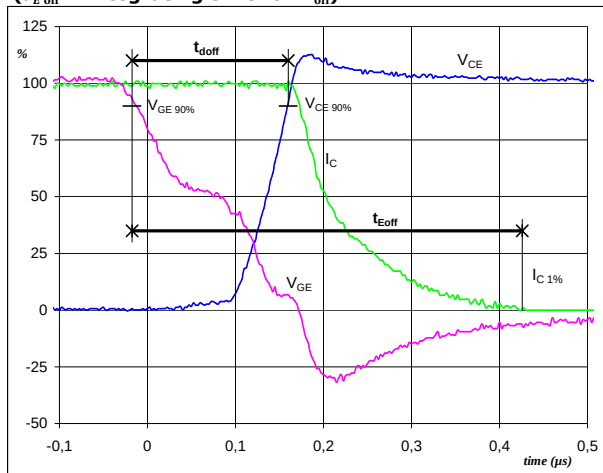
General conditions

T_j	=	125 °C
R_{gon}	=	8 Ω
R_{goff}	=	4 Ω

figure 1.

IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
 (t_{Eoff} = integrating time for E_{off})

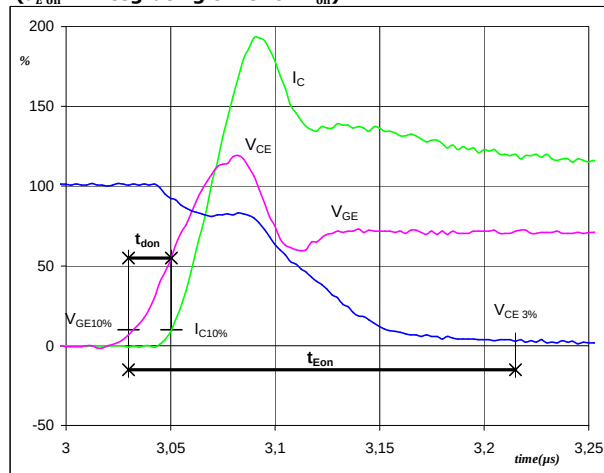


V_{GE} (0%) =	0	V
V_{GE} (100%) =	15	V
V_C (100%) =	300	V
I_C (100%) =	30	A
t_{doff} =	0,17	μ s
t_{Eoff} =	0,44	μ s

figure 2.

IGBT

Turn-on Switching Waveforms & definition of t_{donr} , t_{Eon}
 (t_{Eon} = integrating time for E_{on})

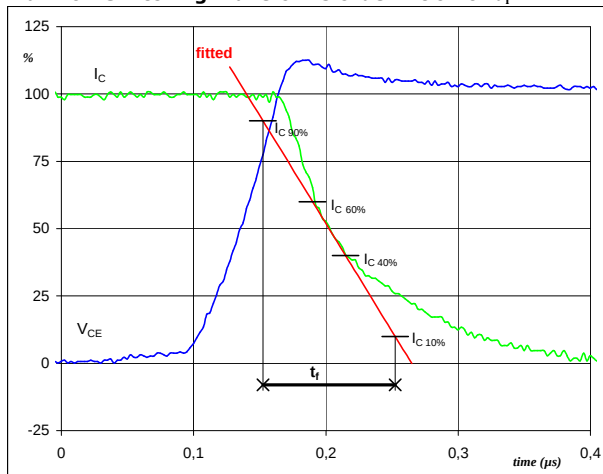


V_{GE} (0%) =	0	V
V_{GE} (100%) =	15	V
V_C (100%) =	300	V
I_C (100%) =	30	A
t_{donr} =	0,02	μ s
t_{Eon} =	0,18	μ s

figure 3.

IGBT

Turn-off Switching Waveforms & definition of t_f

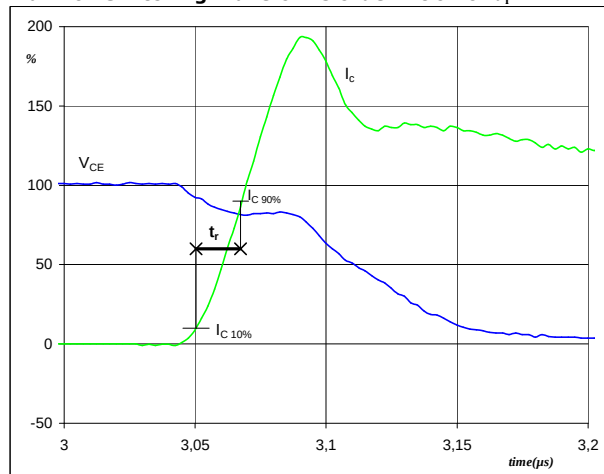


V_C (100%) =	300	V
I_C (100%) =	30	A
t_f =	0,10	μ s

figure 4.

IGBT

Turn-on Switching Waveforms & definition of t_r

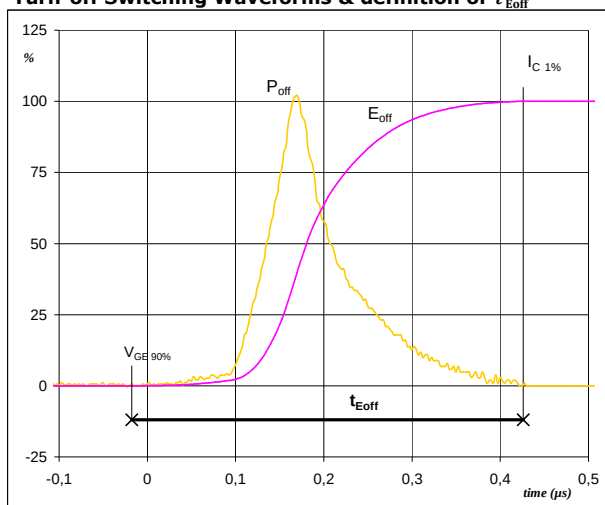


V_C (100%) =	300	V
I_C (100%) =	30	A
t_r =	0,02	μ s



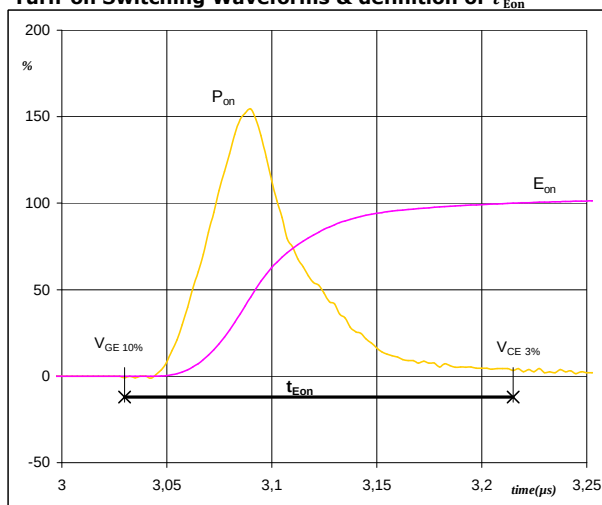
Switching Definitions Inverter

figure 5. IGBT

Turn-off Switching Waveforms & definition of t_{Eoff} 

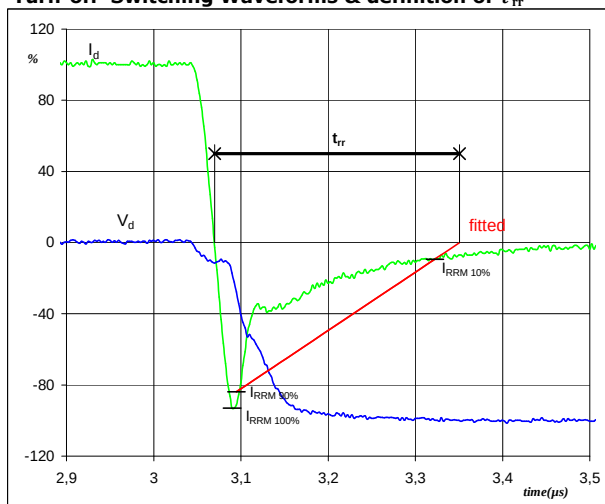
$P_{off} (100\%) = 8,98 \text{ kW}$
 $E_{off} (100\%) = 0,90 \text{ mJ}$
 $t_{Eoff} = 0,44 \text{ }\mu\text{s}$

figure 6. IGBT

Turn-on Switching Waveforms & definition of t_{Eon} 

$P_{on} (100\%) = 8,98 \text{ kW}$
 $E_{on} (100\%) = 0,71 \text{ mJ}$
 $t_{Eon} = 0,18 \text{ }\mu\text{s}$

figure 7. IGBT

Turn-off Switching Waveforms & definition of t_{rr} 

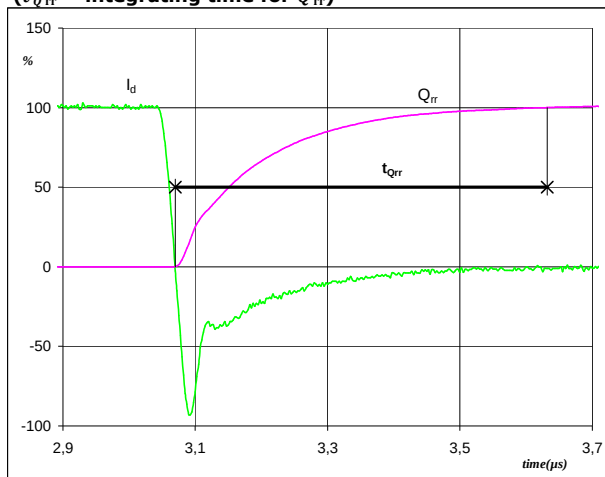
$V_d (100\%) = 300 \text{ V}$
 $I_d (100\%) = 30 \text{ A}$
 $I_{RRM} (100\%) = 28 \text{ A}$
 $t_{rr} = 0,26 \text{ }\mu\text{s}$



Switching Definitions Inverter

figure 8. FWD

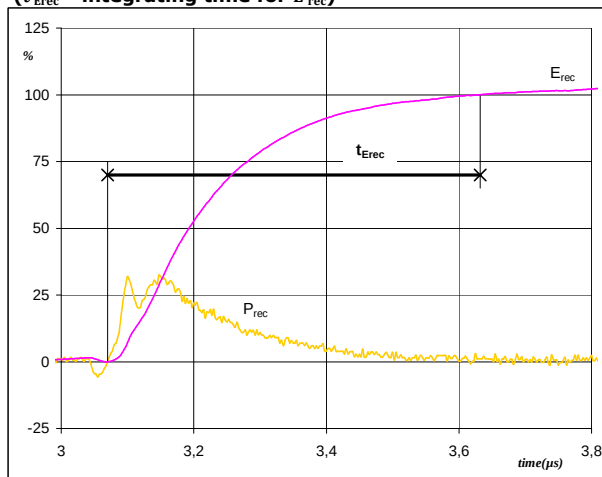
Turn-on Switching Waveforms & definition of t_{Qrr}
(t_{Qrr} = integrating time for Q_{rr})



I_d (100%) =	30	A
Q_{rr} (100%) =	2,45	μC
t_{Qrr} =	0,56	μs

figure 9. FWD

Turn-on Switching Waveforms & definition of t_{Erec}
(t_{Erec} = integrating time for E_{rec})



P_{rec} (100%) =	8,98	kW
E_{rec} (100%) =	0,51	mJ
t_{Erec} =	0,56	μs



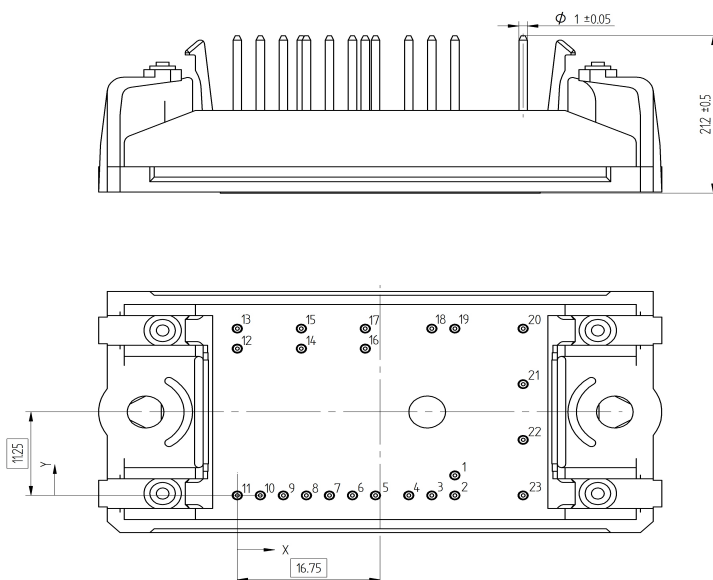
Ordering Code and Marking - Outline - Pinout

Ordering Code & Marking

Version		Ordering Code					
without thermal paste 17mm housing with solder pins		V23990-P546-A20-PM					
	Text	VIN	Date code	Name&Ver	UL	Lot	Serial
		VIN	WWYY	NNNNNNNNVVV	UL	LLLL	SSSS
	Datamatrix	Name&Ver	Lot number	Serial	Date code		
		NNNNNNNNVV	LLLL	SSSS	WWYY		

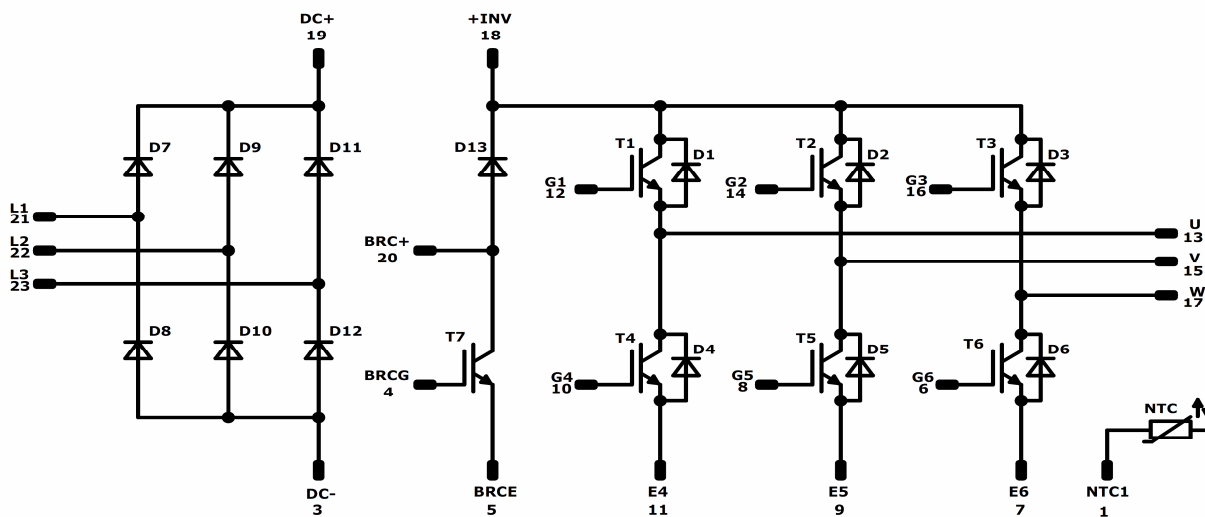
Outline

Pin table			
Pin	X	Y	Function
1	25,5	2,7	NTC1
2	25,5	0	NTC2
3	22,8	0	-DC
4	20,1	0	BRCG
5	16,2	0	BRCE
6	13,5	0	G6
7	10,8	0	E6
8	8,1	0	G5
9	5,4	0	E5
10	2,7	0	G4
11	0	0	E4
12	0	19,8	G1
13	0	22,5	U
14	7,5	19,8	G2
15	7,5	22,5	V
16	15	19,8	G3
17	15	22,5	W
18	22,8	22,5	+INV
19	25,5	22,5	+DC
20	33,5	22,5	BRC+
21	33,5	15	L1
22	33,5	7,5	L2
23	33,5	0	L3



Tolerance of pinpositions: ±0.5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T1-T6	IGBT	600V	30A	Inverter Switch	
D1-D6	FWD	600V	30A	Inverter Diode	
T7	IGBT	600V	20A	Brake Switch	
D13	FWD	600V	20A	Brake Diode	
D7-D12	FWD	1600V	25A	Rectifier Diode	
NTC	NTC			Thermistor	



Packaging instruction			
Standard packaging quantity (SPQ)	135	>SPQ Standard	<SPQ Sample

Handling instruction
Handling instructions for <i>flow</i> 0 packages see vincotech.com website.

Package data
Package data for <i>flow</i> 0 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
V23990-P546-A20-D6-14	15 Apr. 2019	R_{thr} I_{max} P_{tot} clearance values corrected	All

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.